FTDI Chip Announces Advanced Evaluation/Development Modules for USB 3.1 Technology

To complement its FT602 USB 3.1 (Gen 1) video class FIFO IC, which has now gone into full scale production, FTDI Chip has introduced a pair of accompanying hardware modules. The UMFT602A and UMFT602X units enable bridging of a FIFO bus to a USB3.0/1 host and are equipped with either HSMC or FMC (LPC) connectors. They provide engineers with a simple and straight forward platform on which to evaluate the functionality of the 32-bit FT602 devices, which can deliver up to 1920 x 1080 resolution at frame rates of 60fps, with up to 4 video input channels being made available. This should prove particular beneficial in relation to high performance multimedia applications, like streaming of video content captured by HD camera systems.

The UMFT602A/X both incorporate 2 parallel slave FIFO bus protocols - a multi-channel FIFO and a 245 synchronous FIFO. Through their respective integrated FT602 ICs, these modules support USB 3.1 Super Speed (5Gbits/s) as well as USB 2.0 Hi-Speed (480Mbit/s) data transfer rates. They are also capable of delivering data burst rates of up to 400MBytes/s across a 32-bit parallel interface. The UMFT602X has a 70mm x 60mm form factor, while the UMFT602A has dimensions of 78.7mm x 60mm. The design of these modules has been approached in such a way that they can plug directly into the majority of FPGA development platforms on the market, supplied by leading programmable logic vendors like Xilinx and Altera. As daughter cards, the UMFT602A/X units will operate with a FIFO master board which has either a HSMC or FMC connectivity.

About FTDI Chip
FTDI Chip develops innovative silicon solutions that enhance interaction with the latest in global technology. The major objective from the company is to 'bridge technologies' in order to support engineers with highly sophisticated, feature-rich, robust and simple-to-use product platforms. These platforms enable creation of electronic designs with high performance, low peripheral component requirements, low power budgets and minimal board real estate.

FTDI Chip's long-established, continuously expanding Universal Serial Bus (USB) product line boasts such universally recognized product brands as the ubiquitous R-Chip, X-Chip, Hi-Speed and SuperSpeed USB 3.0 series. In addition to both host and bridge chips, it includes highly-integrated system solutions with built-in microcontroller functionality. The company's Embedded Video Engine (EVE) graphic controllers each pack display, audio and touch functionality onto a single chip. The unique, streamlined approach utilised by these ICs allow dramatic reductions in the development time and bill-of-materials costs involved in next generation Human Machine Interface (HMI) implementation. FTDI Chip also provides families of highly-differentiated, speed-optimised microcontroller units (MCUs) with augmented connectivity features, specifically designed with compatibility to its USB and Display product lines in mind. These MCUs are targeted for key applications where they can add value with their superior processing performance and high levels of operational efficiency.

FTDI Chip is a fab-less semiconductor company, partnered with the world's leading foundries. The headquarter is located in Glasgow, UK and is supported with research and development facilities in Glasgow, Singapore and Taipei (Taiwan) plus regional sales and technical support sites in Glasgow, Taipei, Tigard (Oregon, USA) and Shanghai (China).

For more information go to http://www.ftdichip.com.

For further information and reader enquiries:
Susan Smith - FTDI Chip
Unit 1, 2 Seaward Place, Centurion Business Park, Glasgow, G41 1HH, UK
Tel: +44 (0) 141 429 2777 Fax: +44 (0) 141 429 2758
E-mail: marketing@ftdichip.com

Issued by:
Mike Green - Pinnacle Marketing Communications Ltd
Tel: +44 (0)20 84296543
E-mail: m.green@pinnaclemarcom.com
Web: www.pinnacle-marketing.com